# **<b>∴**Caution/Notice

# **⚠**Caution

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### **⚠Caution**

#### ■ Storage and Operation Conditions

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. Also avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed 5 to 40 degrees centigrade and 20 to 70%. Use capacitors within 6 months after delivery.

#### Rating

#### 1. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the V0-p which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.

When DC-rated capacitors are to be used in input circuits from commercial power source (AC filter), be sure to use Safety Recognized Capacitors because various regulations on withstand voltage or impulse withstand established for all equipment should be taken into consideration.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage	Pulse Voltage (1)	Pulse Voltage (2)
Positional Measurement	V0-p	Vo-p	Vp-p	Vp-p	Vp-p

#### 2. Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high-frequency current, pulse current or similar current, it may have self-generated heat due to dielectric loss. In the case of "High Dielectric Constant Type Capacitors," applied voltage load should be such that self-generated heat is within 20 °C under the condition where the capacitor is subjected at an atmosphere temperature of 25 °C. Please contact us if self-generated heat occurs with "Temperature Compensating Type Capacitors".

When measuring, use a thermocouple of small thermal capacity -K of Ø0.1mm under conditions where the capacitor is not affected by radiant heat from other components or wind from surroundings. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.

#### 3. Fail-Safe

Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.

## **⚠**Caution



Continued from the preceding page.

#### Soldering and Mounting

#### 1. Vibration and Impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

#### 2. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

#### 3. Bonding, Resin Molding and Coating

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of the capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case the amount of application, dryness/ hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor may be damaged by the organic solvents and may result, worst case, in a short circuit.

The variation in thickness of adhesive or molding resin or coating may cause an outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

4. Treatment after Bonding, Resin Molding and Coating When the outer coating is hot (over 100 degrees centigrade) after soldering, it becomes soft and fragile, so please be careful not to give it mechanical stress.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

#### ■ Rating

#### 1. Capacitance change of capacitor

In case of F/X7R/X7S/X7T/X8L/Y5V/Z5U char.

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage.

### ■ Soldering and Mounting

#### 1. Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less.

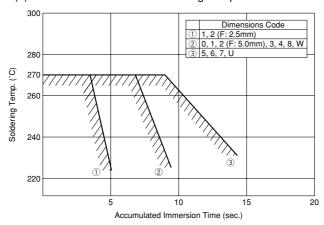
Rinsing time: 5 min. maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

#### 2. Soldering and Mounting

#### (1) Allowable Conditions for Soldering Temperature and Time



Perform soldering within tolerance range (shaded portion).

#### (2) Insertion of the Lead Wire

- · When soldering, insert the lead wire into the PCB without mechanically stressing the lead wire.
- $\cdot$  Insert the lead wire into the PCB with a distance appropriate to the lead space.

	Rated Voltage	DC	25V			DC50V				DC100V		DC250V	DC630V	DC1kV
Dimensions Code	Temp. Char.	X7S	X7R	COG	X7S	X7R	F	Y5V	COG	X7S	X7R		X7R, U2J	
0		224K	104K	A	-	224K	<u>473</u>	103Z	A	_	224K	_	_	-
1		\ <u></u> /	_	102J	-		-	-	102J	_	\/	U 102J	-	-
2		(M 475 K2C)	-	-	(M 475 K5C)	(MK5C)	-	-	-	-	(M) 105 (M) K1C	(U2J) (U2J) (W473) (X7R)	(U2J) (U2J) (W37C) (X7R)	102 JAU (U2J) (U2J) (X7R)
3, 4, W		(M226 K2C	_	_	-	(M335 K5C	-	ı	_	(M225 K1C	-	(M473 J4U (U2J) (M224 K4C (X7R)	(M103 J7U (U2J) (M104 K7C (X7R)	(M472 JAU (U2J) (M333 KAC (X7R)
5, U		ı	-	-	-	-	ı	ı	-	-	_	- (M 474 K4C (X7R)	(U2J) (U2J) (W474 M7C (X7R)	(U2J) (U2J) (M) 104 104 KAC (X7R)
Temperatu Characterist		Marked with code (C0G char.: A, X7S/X7R char.: C, F/Y5V char.: F, U2J char.: U) A part is omitted (Please refer to the marking example.)												
Nominal Capac	itance	Under 10	00pF: Actu	ıal value	100pF a	nd over: M	larked wit	h 3 figures	S					
Capacitance Tol	lerance	Marked with code A part is omitted (Please refer to the marking example.)												
Rated Volta	ıge	Lower ho	Marked with code (DC25V: 2, DC50V: 5, DC100V: 1, DC250V: 4, DC500V: 9, DC630V: 7, DC1kV: A) Lower horizontal line for F char. A part is omitted (Please refer to the marking example.)											
Manufacture Identification		Marked v A part is		Please refe	er to the n	narking ex	ample.)							

# RDE Series (Only for Commercial) Specifications and Test Methods

			Specifi	cations		T		
No.	Ite	m	Temperature Compensating Type	High Dielectric Constant Type		Test Metho	a	
1	Operating Ter Range	mperature	-55 to +125°C	Char. X7R, X7S: -55 to +125°C Char. F: -25 to +85°C Char. Y5V: -30 to +85°C	-			
2	Appearance	earance No defects or abnormalities			Visual inspection			
3	Dimension an	d Marking	See previous pages		Visual inspection, Vernier Caliper			
		Between Terminals	No defects or abnormalities		Temperature	e applied bet ge/Discharge v/, DC100V 3 0V 2 0V 1 v/, DC50V 2 0V, DC50V 2 0V, DC50V 2	ween the terminals	
4	Dielectric Strength	Body Insulation	No defects or abnormalities		The capacitor is plac container with metal diameter so that each short-circuited, is key approximately 2mm as shown in the figurese. between capacitand metal balls. (Ch. current ≤ 50mA)  Rated Voltage  DC25V, DC50V  DC100V, DC250V, DC500V  DC10V, DC630V  DC1kV	balls of 1mm th terminal, pt from the ball re, for 1 to 5 tor terminals arge/Dischar	Approx. 2mm	
5	Insulation Resistance	Between Terminals	Rated Voltage: DC25V, DC50V, 10,000MΩ min. or 500MΩ • μF Rated Voltage: DC250V, DC500 10,000MΩ min. or 100MΩ • μF	F min. whichever is smaller DV, DC630V, DC1kV	The insulation resistance should be measured with DC voltage not exceeding the rated voltage (DC500±50V in case of rated vlotage: DC500V, DC630V, DC1kV) at normal temperature and humic and within 2 min. of charging. (Charge/Discharge current ≤ 50mA)			
6	Capacitance	1	Within the specified tolerance		The capacitance, Q/	D.F. should b	pe measured at 25°C	
7	7 Q/Dissipation Factor (D.F.)		30pF min.: Q≥1,000 30pF max.: Q≥400+20C C: Nominal capacitance (pF)	Char. X7R: 0.025 max. Char. F, Y5V: 0.05 max. Char. X7S: 0.125 max.	at the frequency and Temperature Compe Capacitance Item Frequency Voltage  High Dielectric Cons Capacitance Item Frequency Voltage	C≦1000pF  1±0.1MHz  AC0.5 to 5\ (r.m.s.)	C>1000pF  1±0.1kHz  AC1±0.2V (r.m.s.)  C>10µF	

Continued on the following page.



# RDE Series (Only for Commercial) Specifications and Test Methods

Continued from the preceding page.

			Specifi	cations			
No.	Iter	n	Temperature Compensating Type	High Dielectric Constant Type		Test Method	
		Capacitance Change	Within the specified tolerance (Table A on last column)	Within the specified tolerance (Table B on last column)	min. at each specifie (1) Temperature Con The temperature coe capacitance measure cycling the temperatu through 5 (-55 to +12		
8	Capacitance Temperature	Temperature Coefficient	Within the specified tolerance (Table A on last column)		coefficient and capac A. The capacitance of differences between	titance change as shown in Table thift is calculated by dividing the the maximum and minimum step 1, 3 and 5 by the cap. value in	
0	Characteristics				1	25±2	
					2	-55±3	
					3	25±2	
					5	125±3 25±2	
		Capacitance Drift	Within ±0.2% or ±0.05pF, whichever is larger		(2) High Dielectric Co The ranges of capac 25°C (Char. F: 20°C) ranges as shown in specified ranges. • Pretreatment (for hi Perform a heat treatr		
9	Terminal Strength	Tensile Strength	Termination not to be broken or	loosened	As in the figure, fix the capacitor body, apply the force gradually to each lead in the radial direction of the capacitor until reaching 10N and then keep the force applied for 10±1 sec.		
		Bending Strength	Termination not to be broken or	loosened	Each lead wire should be subjected to a force and then bent 90° at the point of egress in on direction. Each wire is then returned to the or position and bent 90° in the opposite direction rate of one bend per 2 to 3 sec.		
		Appearance	No defects or abnormalities		The capacitor is sold	ered securely to a supporting	
	Vibration	Capacitance	Within the specified tolerance		terminal and a 10 to	55Hz vibration of 1.5mm peak-	
10	Resistance	Q/D.F.	30pF min.: Q≥1,000 30pF max.: Q≥400+20C C: Nominal capacitance (pF)	Char. X7R: 0.025 max. Char. F, Y5V: 0.05 max. Char. X7S: 0.125 max.	mutually perpendicul	plied for 6 hrs. total, 2 hrs. in each ar direction. Allow 1 min. to cycle 0Hz to 55Hz and the converse.	
11	Solderability of Leads  Lead wire should be soldered with uniform coating on the axial direction over 3/4 of the circumferential direction.		(JIS-K-8101) solutior then into molten sold depth of dipping is up terminal body. Temp. of solder: 245±5	vacitor is dipped into a 25% ethano n of rosin (JIS-K-5902) and er for 2±0.5 sec. In both cases the note about 1.5mm to 2mm from the C Lead Free Solder (Sn-3.0Ag-0.5Cu C H60A or H63A Eutectic Solder			
		Appearance	No defects or abnormalities		The lead wire is imm	ersed in the melted solder 1.5mm	
40	Resistance to	Capacitance Change	Within ±2.5% or ±0.25pF (whichever is larger)	Char. X7R, X7S: Within ±10% Char. F, Y5V: Within ±20%	to 2mm from the mai sec.	n body at 350±10°C for 3.5±0.5	
12	Soldering Heat	Dielectric Strength (Between Terminals)	No defects		The specified items are measured after 24±2 hrs. • Pretreatment (for high dielectric constant type) Perform a heat treatment at 150+0/-10°C for 1 hr., and then let sit at room temperature for 24±2 hrs.		

Continued on the following page.  $\begin{tabular}{|c|c|c|c|} \hline \end{tabular}$ 



# RDE Series (Only for Commercial) Specifications and Test Methods

Ontinued from the preceding page.

Na	lto	<b>m</b>	Specifi	cations		Toot Mothod		
No.	Itei	11	Temperature Compensating Type	High Dielectric Constant Type		Test Method		
		Appearance	No defects or abnormalities					
		Capacitance Change	Within ±5% or ±0.5pF (whichever is larger)	Char. X7R, X7S: Within ±12.5% Char. F, Y5V: Within ±30%	The capacit	for should be subjected to 5 to	emperature	
		Q/D.F.	30pF min.: Q≥350 10pF to 30pF: Q≥275+5C/2 10pF max.: Q≥200+10C	Char. X7R: 0.05 max. Char. F, Y5V: 0.075 max.	Remove an then measu			
	Temperature		C: Nominal capacitance (pF)	Char. X7S: 0.2 max.	Step 1	Temperature (°C) Min. Operating Temp. ±3	Time (min)	
13	Cycle	Insulation Resistance	Rated Voltage: DC25V, DC50V, 1,000MΩ, 50MΩ • μF min. (wh Rated Voltage: DC250V, DC500 1,000MΩ, 10MΩ • μF min. (wh	nichever is smaller) DV, DC630V, DC1kV	2 3 4	Room Temp.  Max. Operating Temp. ±3  Room Temp.  ent (for high dielectric consta	3 max. 30±3 3 max.	
		Dielectric Strength (Between Terminals)	No defects or abnormalities		Perform a h	neat treatment at 150+0/-10°C at room temperature for 24±2	ofor 1 hr., and	
		Appearance	No defects or abnormalities					
		Capacitance Change	Within ±5% or ±0.5pF (whichever is larger)	Char. X7R, X7S: Within ±15% Char. F, Y5V: Within ±30%	Set the cap	acitor at 40±2°C and relative	humidity of	
14	Humidity (Steady State)	Q/D.F.	30pF min.: Q≧350 10pF to 30pF: Q≥275+5C/2 10pF max.: Q≥200+10C C: Nominal capacitance (pF)	Char. X7R: 0.05 max. Char. F, Y5V: 0.075 max. Char. X7S: 0.2 max.	90 to 95% for 500±26 hrs.  Remove and set for 24±2 hrs. at room temperatuthen measure.  • Pretreatment (for high dielectric constant type)			
		Insulation Resistance	Rated Voltage: DC25V, DC50V, 1,000MΩ, 50MΩ • μF min. (wh Rated Voltage: DC250V, DC500 1,000MΩ, 10MΩ • μF min. (wh	nichever is smaller) DV, DC630V, DC1kV	<ul> <li>Perform a heat treatment at 150+0/-10°C for 1 hr., and then let sit at room temperature for 24±2 hrs.</li> </ul>			
		Appearance	No defects or abnormalities					
		Capacitance Change	Within ±7.5% or ±0.75pF (whichever is larger)	Char. X7R, X7S: Within ±15% Char. F, Y5V: Within ±30%	Tippiy the rated voltage for 500_ (		at 40±2°C and	
15	Humidity Load	Q/D.F.	30pF min.: Q≥200 30pF max.: Q≥100+10C/3 C: Nominal capacitance (pF)	Char. X7R: 0.05 max. Char. F, Y5V: 0.075 max. Char. X7S: 0.2 max.	then measu (Charge/Dis	scharge current ≦50mA)	·	
		Insulation Resistance	Rated Voltage: DC25V, DC50V, 500MΩ or 25MΩ • μF min. (wh Rated Voltage: DC250V, DC500 1,000MΩ or 10MΩ • μF min. (v	nichever is smaller) VV, DC630V, DC1kV	Pretreatment (for high dielectric constant type)     Perform a heat treatment at 150+0/-10°C for 1 hr.,     then let sit at room temperature for 24±2 hrs.			
		Appearance	No defects or abnormalities		Apply voltage	ge in Table for $1000^{+48}_{-0}$ hrs.	at the	
		Capacitance	Within ±3% or ±0.3pF	Char. X7R, X7S: Within ±15% (Rated Voltage: DC630V or less)	maximum o Remove an	perating temperature±3°C. d set for 24±2 hrs. at room te ire. (Charge/Discharge currer	emperature,	
		Change	(whichever is larger)	Within ±20%	Tiated Voltage		Voltage	
	High			(Rated Voltage: DC1kV) Char. F, Y5V: Within ±30%	Temperature Compensatin		e rated voltage	
16	Temperature		30pF min.: Q≧350		Туре	DC630V, DC1kV 120% of the	e rated voltage	
	Load	Q/D.F.	10pF to 30pF: Q≥275+5C/2 10pF max.: Q≥200+10C C: Nominal capacitance (pF)	Char. X7R: 0.05 max. Char. F, Y5V: 0.075 max. Char. X7S: 0.2 max.	High Dielectr Constant Typ	DC100V, DC250V	e rated voltage	
		Insulation Resistance	Rated Voltage: DC25V, DC50V, 1,000MΩ, 50MΩ • μF min. (wh Rated Voltage: DC250V, DC500 1,000MΩ, 10MΩ • μF min. (wh	Appy test vo	DC1kV 110% of the ent (for high dielectric consta oltage for 1 hr., at test temper d set for 24±2 hrs. at room to	rature.		
		Appearance	No defects or abnormalities			or should be fully immersed,		
17	Solvent Resistance	Marking	Legible		reagent at 2 gently. Marl	20 to 25°C for 30±5 sec. and king on the surface of the cap by be visually examined.	then removed	

#### Table A

		No. of collystees	Capacitance Change from 25°C (%)							
Char.	Nominal Values	−55°C		-30	0°C	-10°C				
		(ppm/°C) *1	Max.	Min.	Max.	Min.	Max.	Min.		
	COG	0±30	0.58	-0.24	0.40	-0.17	0.25	-0.11		
	U2J	-750±120	8.78	5.04	6.04	3.47	3.84	2.21		

<sup>\*1:</sup> Nominal values denote the temperature coefficient within a range of 25 to 125°C

#### Table B

Char.	Temp. Range	Reference Temp.	Cap. Change Rate
X7R	–55 to +125°C		Within ±15%
X7S	-55 t0 +125 0	25°C	Within ±22%
Y5V	-30 to + 85°C		Within ±62%
F	-25 to + 85°C	20°C	Within ±30%

#### Packaging

Two types of packaging for monolithic ceramic capacitors are available.

#### 1. Bulk Packaging

Minimum Quantity

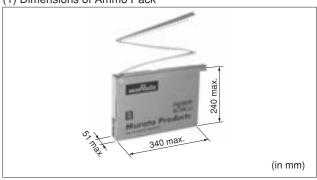
Dimensions Code	Dimensions (LXW)	Minimum Quantity (pcs./Bag)*
0	3.6×3.5mm or 4.0×3.5mm or 5.0×3.5mm (Depends on Part Number)	
1	4.0×3.5mm or 4.5×3.5mm or 5.0×3.5mm (Depends on Part Number)	
2	5.0×3.5mm or 5.5×4.0mm or 5.7×4.5mm (Depends on Part Number)	
3	5.0×4.5mm or 5.5×5.0mm or 6.0×5.5mm (Depends on Part Number)	500
4	7.5×5.5mm	500
5	7.5×7.5mm or 7.5×8.0mm (Depends on Part Number)	
6	10.0×10.0mm	
8	7.5×5.5mm	
7	12.5×12.5mm	100
U	7.7×12.5mm or 7.7×13.0mm (Depends on Part Number)	200
W	5.5×7.5mm or 6.0×8.0mm (Depends on Part Number)	500

Please order with an integral multiple of the minimum quantity above.

Please check our website 'Product details'.

#### 2. Tape Carrier Packaging





#### (2) Minimum Quantity

Dimensions Code	Dimensions (LXW)	Minimum Quantity (pcs./Ammo Pack)*
0	3.6×3.5mm or 4.0×3.5mm or 5.0×3.5mm (Depends on Part Number)	
1	4.0×3.5mm or 4.5×3.5mm or 5.0×3.5mm (Depends on Part Number)	
2	5.0×3.5mm or 5.5×4.0mm or 5.7×4.5mm (Depends on Part Number)	2000
3	5.0×4.5mm or 5.5×5.0mm or 6.0×5.5mm (Depends on Part Number)	
4	7.5×5.5mm	
5	7.5×7.5mm or 7.5×8.0mm (Depends on Part Number)	2000
6	10.0×10.0mm	1500
8	7.5×5.5mm	1500
U	7.7×12.5mm or 7.7×13.0mm (Depends on Part Number)	1000
W	5.5×7.5mm or 6.0×8.0mm (Depends on Part Number)	1500

Please order with an integral multiple of the minimum quantity above.

Please check our website 'Product details'.

"Minimum Quantity" means the numbers of units of each delivery or order. The quantity should be an integral multiple of the "minimum quantity". (Please note that the actual delivery quantity in a package may change sometimes.)

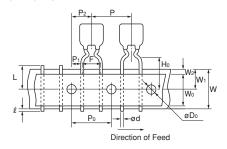
<sup>\*</sup> Minimum Quantity may change depends on part number.

st Minimum Quantity may change depends on part number.

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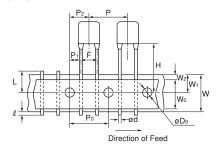
## ■ Taping Dimensions

## Inside Crimp Taping



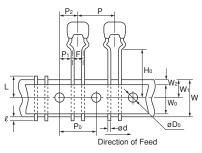
Dimensions and Lead Style Code
0M1
1M1
2M1
2M2
3M1
3M2
4M1
4M2
8M1
8M2
WM1

## Straight Taping

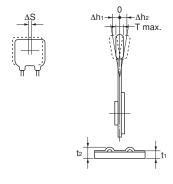


Dimensions and Lead Style Code
1DB
2DB
3DB
5E1
5E2
6E1
6E2
UE1

## Outside Crimp Taping



Dimensions and Lead Style Code
0\$1
1\$1
2\$1
2\$2
3S1
3S2



Item	Code	Dimensions (mm)
Pitch of Component	Р	12.7±1.0
Pitch of Sprocket Hole	Po	12.7±0.2
Lead Spacing	F	2.5 <sup>+0.4</sup> <sub>-0.2</sub> (DB) (S1) (S2)
		5.0 +0.6
Length from Hole Center to Component Center	P <sub>2</sub>	6.35±1.3
	_	3.85±0.7
Length from Hole Center to Lead	P <sub>1</sub>	5.1±0.7 (DB) (S1) (S2)
	254±1.5	5 Total length of components pitch × 2
Body Dimension	[	Depends on Part Number
Deviation Along Tape, Left or Right Defect	ΔS	±2.0
Carrier Tape Width	W	18.0±0.5
Position of Sprocket Hole	W <sub>1</sub>	9.0+0
Lead Distance between Reference and Bottom Plane	Ho	16.0±0.5 (M1) (S1)
		20.0±0.5 (M2) (S2)
For Straight Lead Type	Н	20±0.5 (E2),17.5±0.5 (E1),16±0.5 (D
Diameter of Sprocket Hole	D <sub>0</sub>	4.0±0.1
Lead Diameter	d	0.5±0.05
Total Tape Thickness	t1	0.6±0.3
Total Thickness of Tape and Lead Wire	t2	1.5 max.
Body Thickness	Т	Depends on Part Number
Deviation Across Tape	Δh1 Δh2	2.0 max. Dimensions Code: W,
		1.5 max. RHD Series
		1.0 max. except as above
Portion to Cut in Case of Defect	L	11.0+0
Protrusion Length	l	0.5 max.
Hold Down Tape Width	Wo	9.5 min.
Hold Down Tape Position	W <sub>2</sub>	1.5±1.5
Coating Extension	Depends on Dimensions	